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Team from Purdue University named as winners in Phase One of the SRC/SIA IC Design Challenge

Phase One Winners

Team	Design Title	University	Faculty Leader	Prize
19	High-Speed Inter- and Intra-Chip Wireless Interconnect Using Integrated U-band RF Transceiver	Purdue University	Byunghoo Jung	First Place - \$10,000
35	Ultra-Low Power UWB Food Safety-Monitoring System	University of Minnesota	Ramesh Harjani	Second Place - \$5,000
2	A Tunable Multiband RF MEMS Transceiver Front-End	Carnegie Mellon University	Tamal Mukherjee	Third Place - \$3,000

All cash awards will be provided as gifts to the winning universities in the name of the faculty team leader to be used in support of IC design education programs at their university.

In addition to the cash awards, these teams will be invited to compete in Phase 2 of the Design Challenge where they will be able to fabricate and test their circuits using Jazz Semiconductor's SBC18 180nm SiGe technology. Formal recognition for these Phase 1 awards will be made at SRC TECHON 2008 in Austin, TX in September.

In addition to the winning teams listed above, another five teams were also chosen by the judges to participate in Phase2. All [eight teams](#) will present posters at TECHCON 2008.

The eight teams will finalize their designs by mid-May and submit them to Jazz for fabrication. Fabricated devices will be returned to the teams in September after which they will test/characterize their circuits and submit a final report for judging. The top three overall Design Challenge winners (Phase 2 winners) will be announced in early 2009 and will receive awards of \$25K, \$15K, and \$10K for first, second and third place respectively.

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